

Altera Device Package Information

04R-00316-1.0

1932-Pin FineLine Ball-Grid Array (FBGA) - Flip Chip - Dual-Piece Lid - A:3.80

- All dimensions and tolerances conform to ASME Y14.5M 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

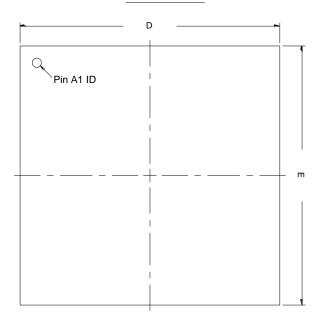
Package Information		
Description	Specification	
Ordering Code Reference	F	
Package Acronym	FBGA	
Substrate Material	ВТ	
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)	
JEDEC Outline Reference	MS-034 Variation: AAW-1	
Lead Coplanarity	0.010 inch (0.25 mm)	
Weight	24.6 g (Typ.)	
Moisture Sensitivity Level	Printed on moisture barrier bag	

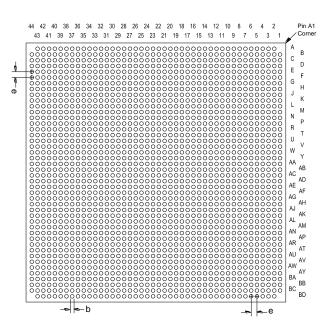
Symbol	Millimeters		
	Min.	Nom.	Max.
Α	3.40	3.60	3.80
A1	0.40	0.50	0.60
A2	2.80	3.10	3.40
A3	1.40	1.50	1.60
D		45.00 BSC	
E	45.00 BSC		
b	0.50	0.60	0.70
е		1.00 BSC	

Package Outline

TOP VIEW

BOTTOM VIEW







Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
June 2011	1.0	Initial release



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